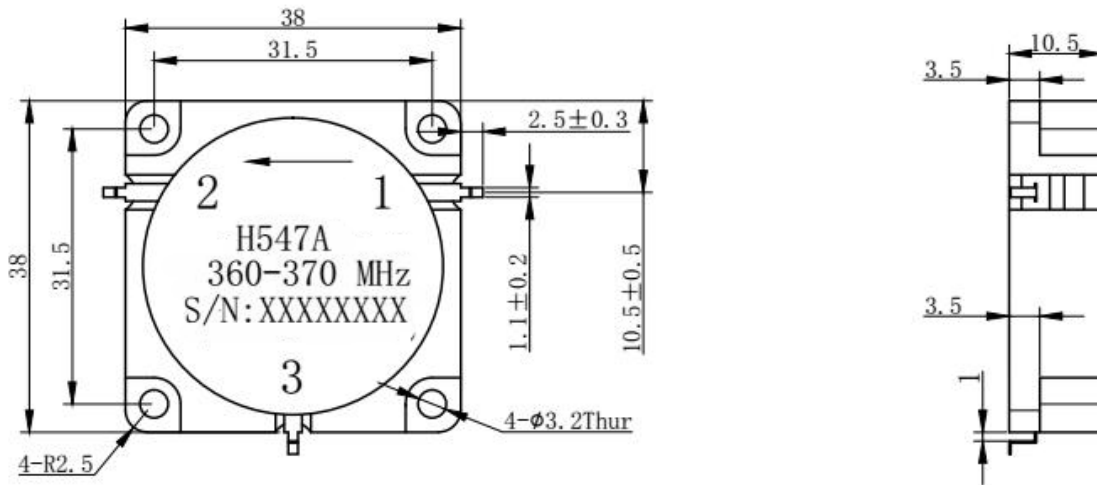


## 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

## 2.Dimensions Unit:mm



## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H547A0.0[360-370]MHz	0.360	0.370	0.365	0.010	23	0.25	1.15	150	
H547A0.0[395-435]MHz	0.385	0.435	0.4050	0.040	19	0.45	1.25	150	-60
H547A0.0[415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	200	
H547A0.0[470-520]MHz	0.470	0.520	0.4950	0.050	20	0.35	1.22	200	
H547A0.0[566-678]MHz	0.566	0.678	0.6220	0.112	20	0.45	1.22	150	-65